

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology
- ★ 100% EAS Guaranteed

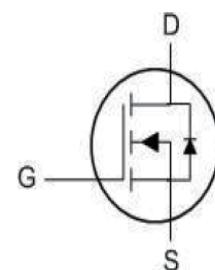
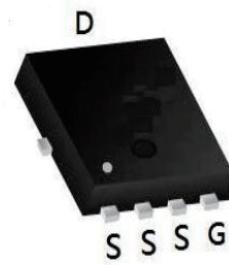
**Product Summary****RoHS**

BVDSS	RDSON	ID
30V	3.8mΩ	80A

**Description****PRPAK5\*6 Pin Configuration**

The 80N03F is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The 80N03F meet the RoHS and Green Product, requirement 100% EAS guaranteed with full function reliability approved.

**Absolute Maximum Ratings**

Symbol	Parameter	Limit	Unit
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current-Continuous	80	A
$I_D (100^\circ\text{C})$	Drain Current-Continuous( $T_c=100^\circ\text{C}$ )	46	A
$I_{DM}$	Pulsed Drain Current <sup>(Note 1)</sup>	200	A
$P_D$	Maximum Power Dissipation	65	W
	Derating factor	0.52	W/ $^\circ\text{C}$
$E_{AS}$	Single pulse avalanche energy <sup>(Note 5)</sup>	150	mJ
$T_J, T_{STG}$	Operating Junction and Storage	-55 To 150	$^\circ\text{C}$

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	-	0.56	$^\circ\text{C/W}$

Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

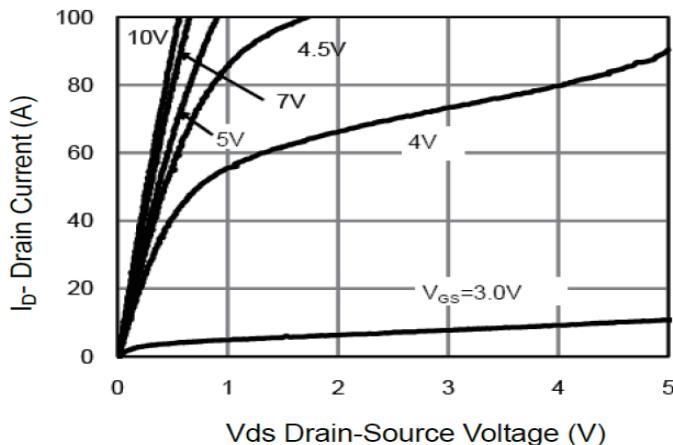
Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	-	-	V
$I_{\text{DS}}^{\text{SS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b> (Note 3)						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1	1.6	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	-	3.8	5.0	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=20\text{A}$	-	6.9	11.0	
$g_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=20\text{A}$	20	-	-	S
<b>Dynamic Characteristics</b> (Note 4)						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	1400	-	PF
$C_{\text{oss}}$	Output Capacitance		-	205	-	PF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	177	-	PF
<b>Switching Characteristics</b> (Note 4)						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=15\text{V}, I_{\text{D}}=20\text{A}$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=6.0\Omega$	-	9	-	nS
$t_r$	Turn-on Rise Time		-	8	-	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		-	28	-	nS
$t_f$	Turn-Off Fall Time		-	5	-	nS
$Q_g$	Total Gate Charge	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=20\text{A}, V_{\text{GS}}=10\text{V}$	-	32.3	-	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	4.9	-	nC
$Q_{\text{gd}}$	Gate-Drain Charge		-	6.9	-	nC
<b>Drain-Source Diode Characteristics</b>						
$V_{\text{SD}}$	Diode Forward Voltage (Note 3)	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=20\text{A}$	-	0.85	1.2	V
$I_s$	Diode Forward Current (Note 2)		-	-	65	A
$t_{\text{rr}}$	Reverse Recovery Time	$T_J = 25^\circ\text{C}, IF = 20\text{A}$ $dI/dt = 100\text{A}/\mu\text{s}$ (Note <sup>3</sup> )	-	-	27	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		-	-	20	nC
$t_{\text{on}}$	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

## Note :

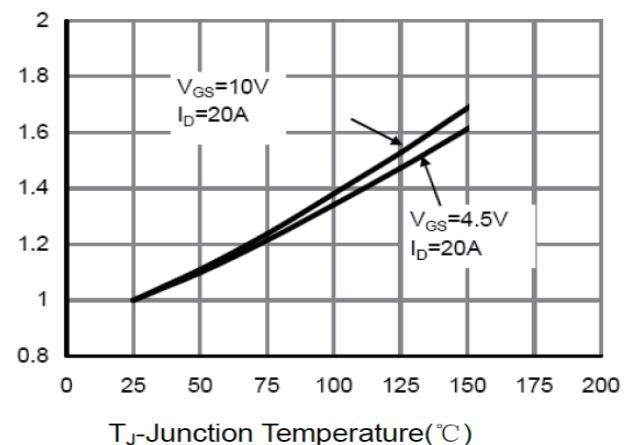
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. EAS condition:  $T_J=25^\circ\text{C}, V_{\text{DD}}=15\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$ .

### Typical Electrical and Thermal Characteristics (Curves)

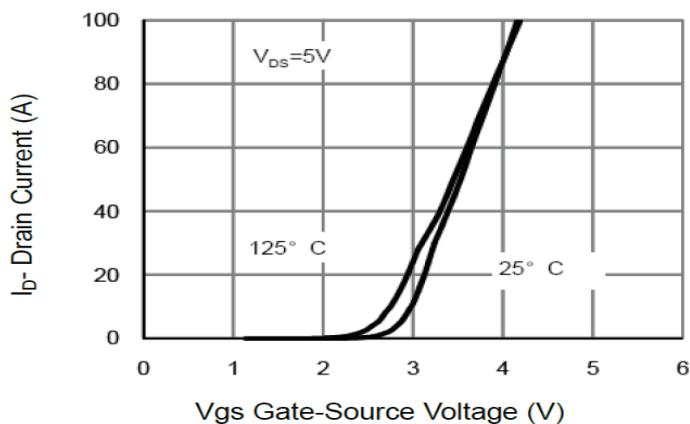
**Figure 1: Output Characteristics**



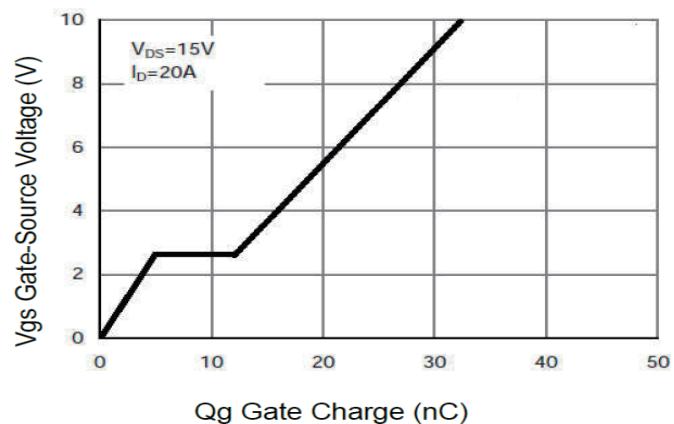
**Figure 4:  $R_{DS(on)}$ -Junction Temperature**



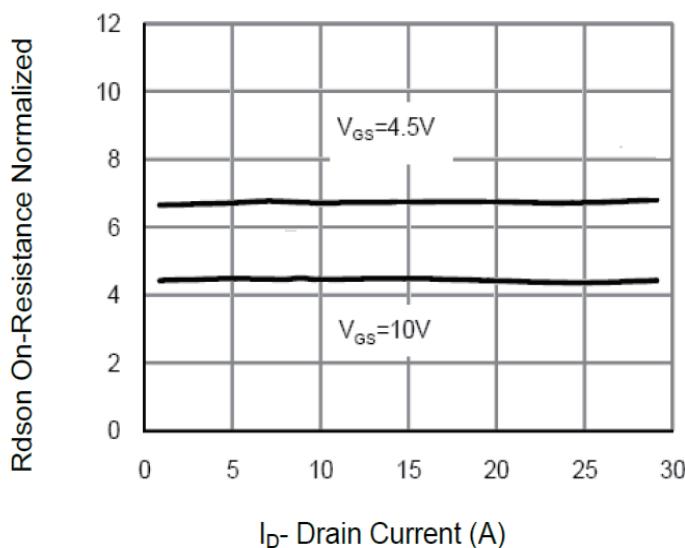
**Figure 2: Transfer Characteristics**



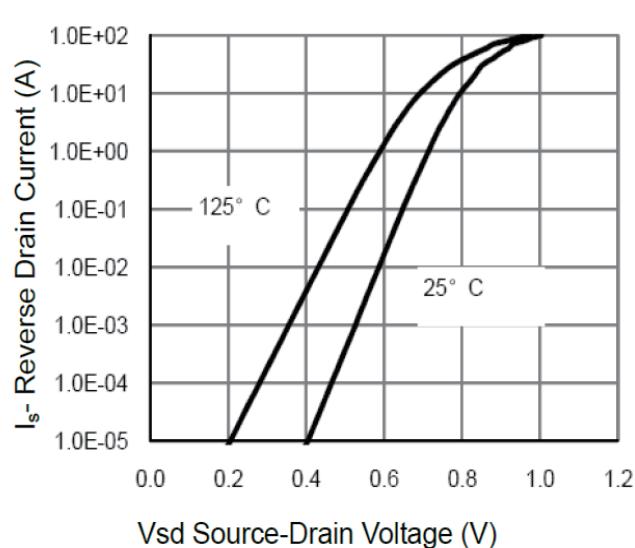
**Figure 5: Gate Charge**



**Figure 3:  $R_{DS(on)}$ - Drain Current**



**Figure 6: Source-Drain Diode Forward**



### Typical Performance Characteristics

Figure 7: Capacitance vs Vds

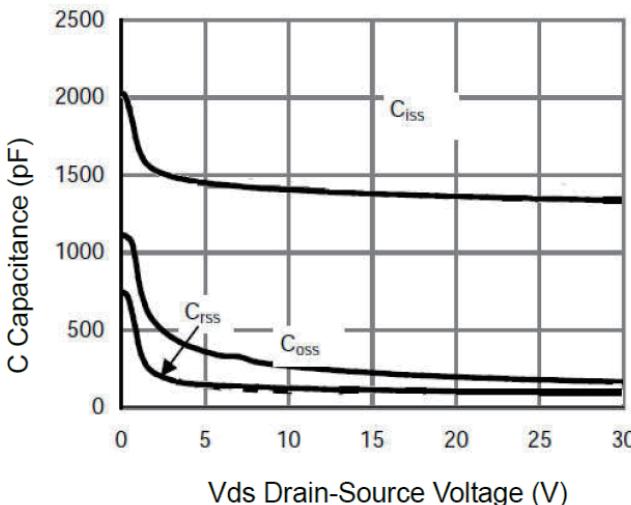


Figure 9: BVDSS vs Junction Temperature

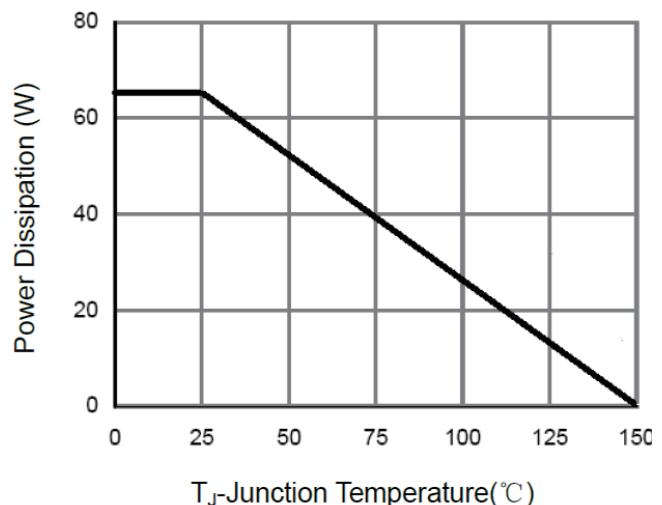


Figure 8: Safe Operation Area

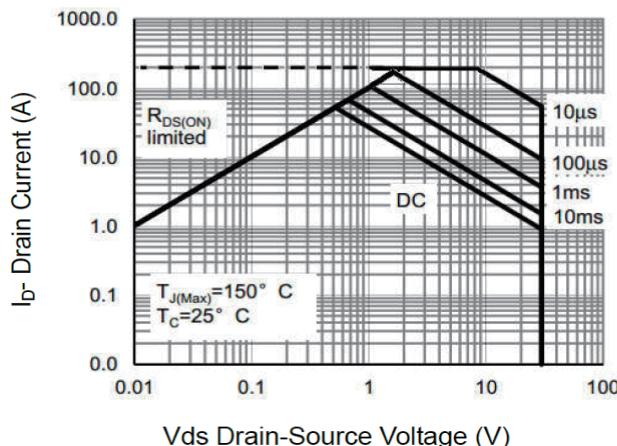


Figure 10: VGS(th) vs Junction Temperature

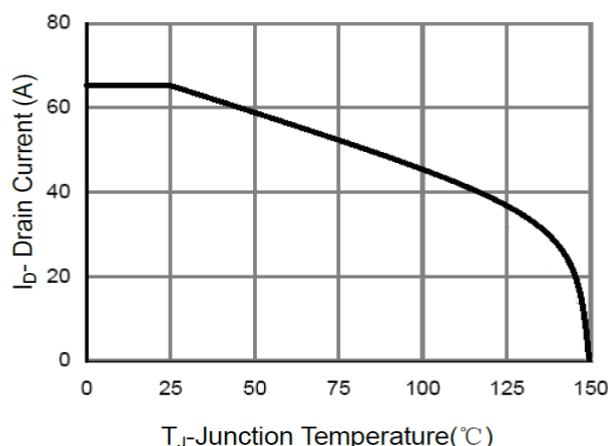
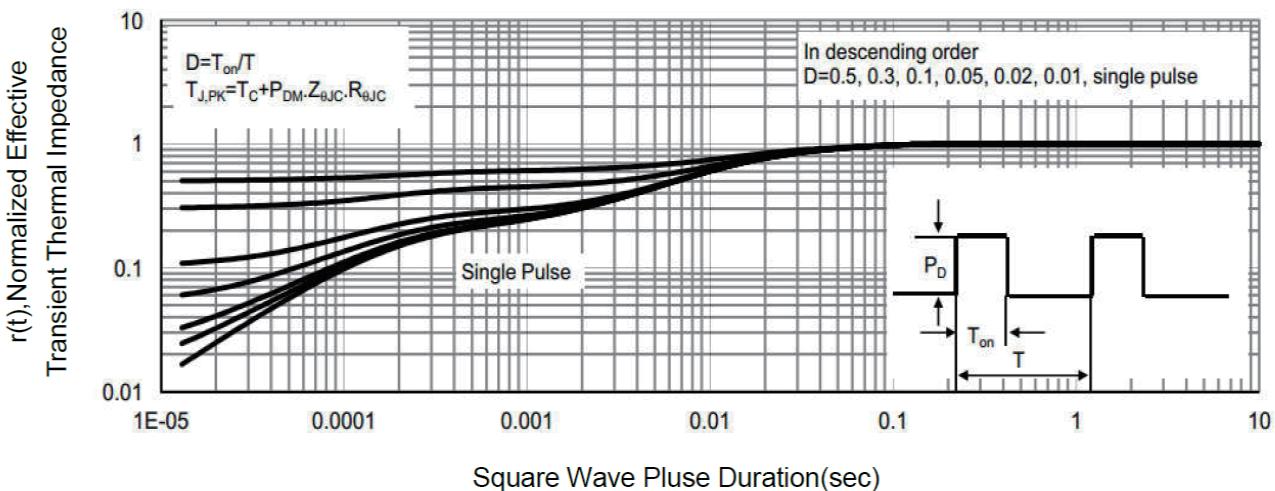


Figure 11: Normalized Maximum Transient Thermal Impedance



## Test Circuit

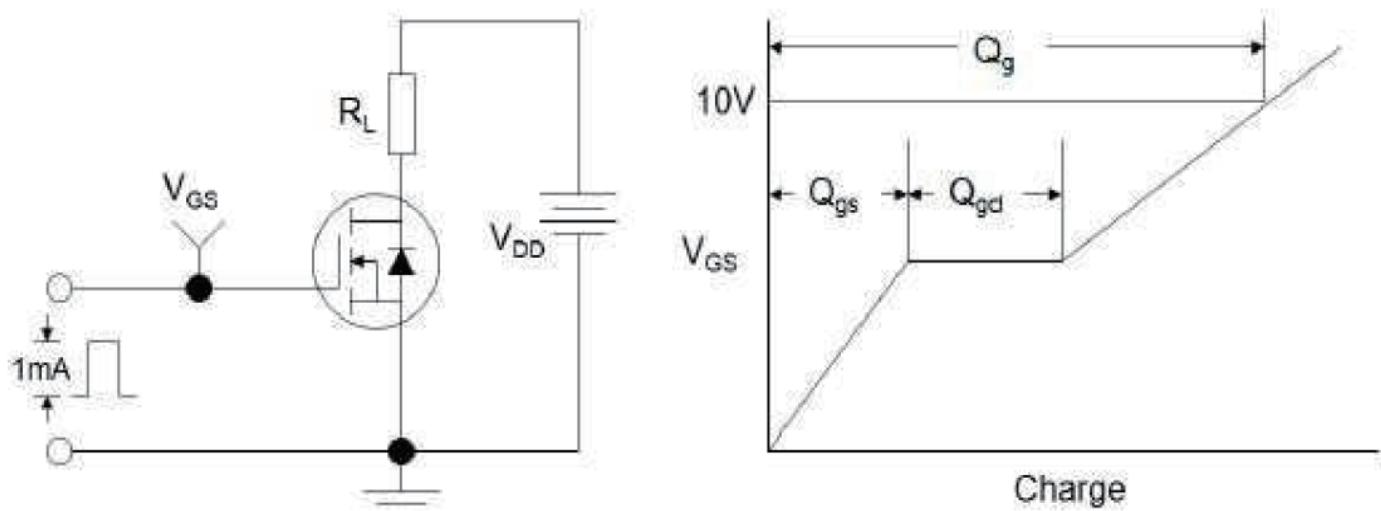


Figure 1: Gate Charge Test Circuit & Waveform

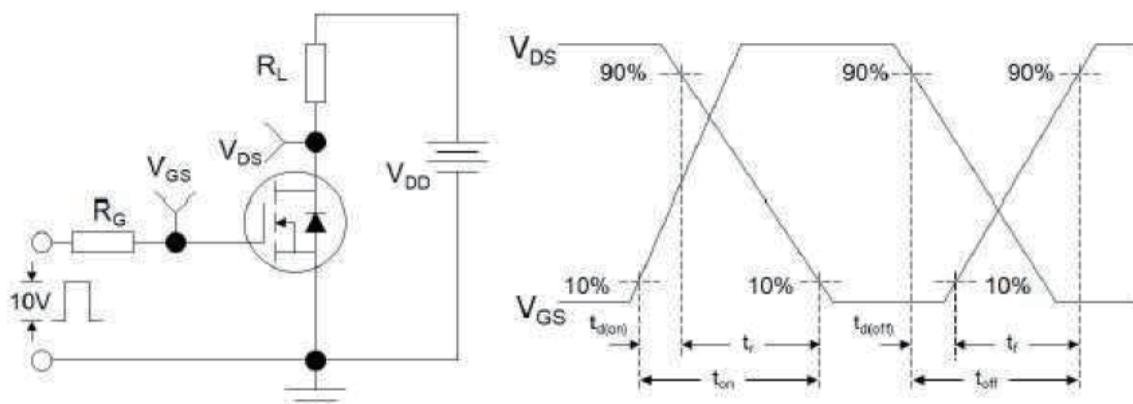


Figure 2: Resistive Switching Test Circuit & Waveforms

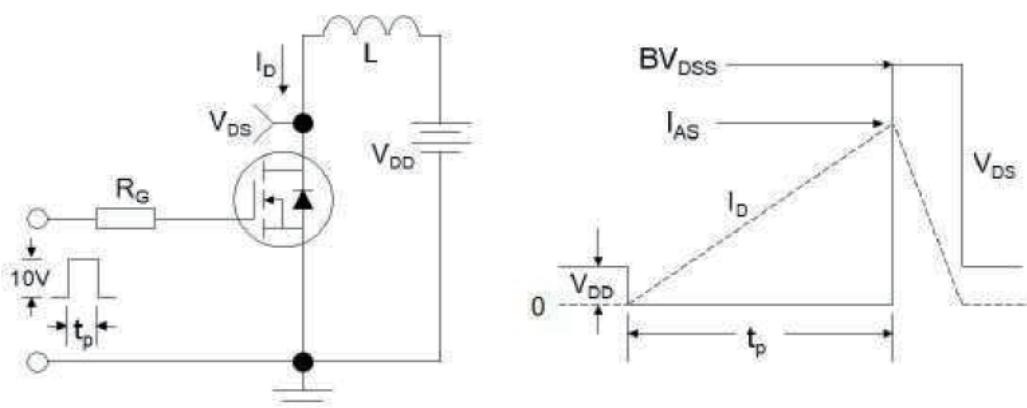
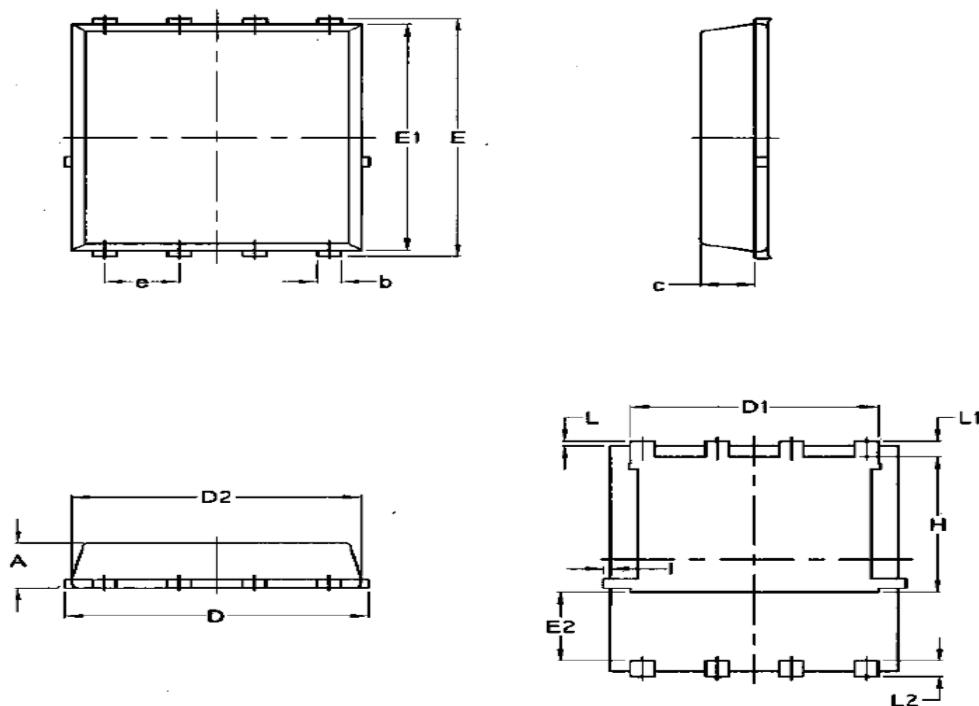


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

## Package Mechanical Data-DFN5\*6-8L-JQ Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.097	0.0324	0.082
D	4.8	5.4	0.189	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.8	5	0.189	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.6	/	0.063	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.002	0.0098
L1	0.38	0.5	0.015	0.0197
L2	0.38	0.5	0.015	0.0197
H	3.3	3.5	0.1299	0.1378
I	/	0.18	/	0.007